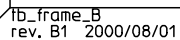
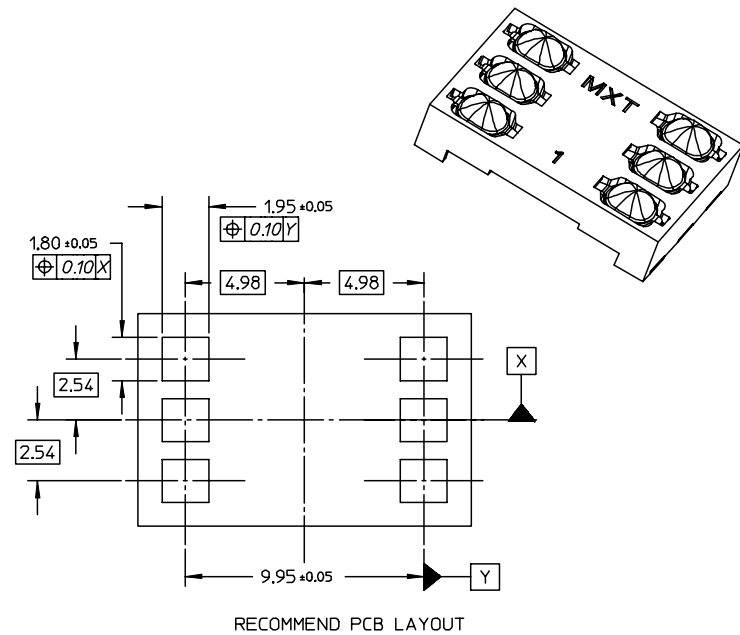
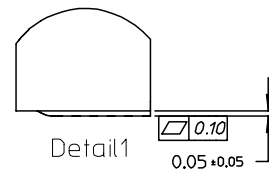
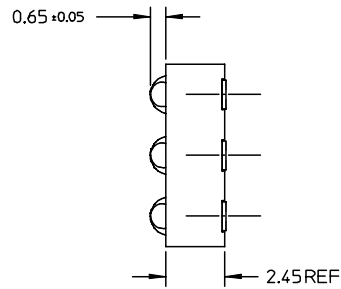
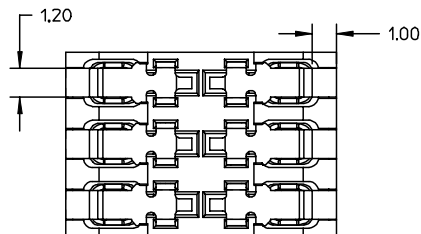
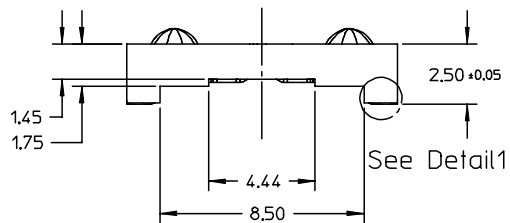
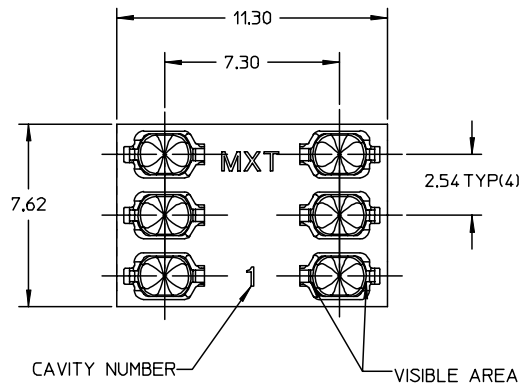


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NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK
 TERMINAL:COPPER ALLOY

2.PLATING:

SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

3.PACKAGING: TAPE REEL

4.PRODUCT SPECIFICATION REFER TO PS-67687-001

EC NO: SH2003-0071 DRWN: SSUN 2003/07/01 CHKD: 2003/07/04 APPR: SHUANG 2003/07/04 A	DESCRIPTION REV	QUALITY SYMBOLS ▽ = 0 ◁ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	REVISE ON CAD ONLY		
					DIMENSION STYLE MM ONLY		TITLE SIM CARD CONNECTOR SALES DRAWING			
			4 PLACES	± ---	± ---	DRAWN BY DATE		SSUN 2003/06/16		
			3 PLACES	± ---	± ---	CHECKED BY DATE				
			2 PLACES	± 0.2	± ---	APPROVED BY DATE		MATERIAL NO. 676872501 DOCUMENT NO. SD-67687-801 SHEET NO. 1 OF 1		
			1 PLACE	± 0.25	± ---					
			ANGULAR ± 3 °		MOLEX MOLEX INCORPORATED					
			DRAFT WHERE APPLICABLE							
			MUST REMAIN WITHIN DIMENSIONS							
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					B					